

Amendments to the Claims:

This listing of claims will replace the listing of claims as pending in the present application:

Listing of Claims:

Claim 1 (original): A method of patterning a functional material onto a substrate, comprising the steps of (a) applying a layer of functional material to at least one major surface of said substrate; (b) applying a layer of protective material, soluble in a solvent in which the functional material is insoluble, over said layer of functional material; (c) removing areas of said layers of protective and functional materials in well-defined regions on the substrate; and (d) removing the remaining exposed protective material from the substrate by dissolution in said solvent.

Claim 2 (original): The method of claim 1, wherein in step (c) said layers of functional material and said layer of protective material are removed from the well-defined regions by laser ablation.

Claims 3-27 (canceled).

Claim 28 (new): A method according to claim 1, wherein after step (c) a second functional material is deposited at least onto the substrate in the well-defined regions; a further layer of protective material, soluble in a solvent in which the second functional material is insoluble, is applied over said second functional material; areas of said materials that overlie the edge of the well-defined regions are removed and after step (d) the remainder

of said layer of protective material and any of the second functional material other than in the well-defined regions are removed.

Claim 29 (new): A method according to claim 28, wherein said areas of said materials that overly the edge of the well-defined regions are removed by laser ablation.

Claim 30 (new): A method according to claim 28, wherein after step (d) the remainder of said layer of protective material and any of the second functional material other than in the well-defined regions are removed using a lift off process.

Claim 31 (new): A method according to claim 28, comprising further steps of patterning a further functional material to the substrate, the further steps comprising repeating the steps of claim 28 for the further functional material.

Claim 32 (new): A method according to claim 1, wherein in step (c) the layer of functional material is not completely removed from the well-defined areas on the substrate.

Claim 33 (new): A method according to claim 1, wherein said substrate comprises glass.

Claim 34 (new): A method according to claim 1, wherein said substrate comprises silicon.

Claim 35 (new): A method according to claim 1, wherein said substrate comprises plastics material.

Claim 36 (new): A method according to claim 1, wherein said substrate comprises a charge injection layer.

Claim 37 (new): A method according to claim 36, wherein said charge injection layer is patterned.

Claim 38 (new): A method according to claim 1, wherein said at least one major surface of the substrate is structured.

Claim 39 (new): A method according to claim 38, wherein said at least one major surface of the substrate comprises a raised wall structure, which may be of inorganic, organic, or metal material.

Claim 40 (new): A method according to claim 1, wherein said protective material comprises organic material.

Claim 41 (new): A method according to claim 40, wherein said protective material comprises a water soluble polymer.

Claim 42 (new): A method according to claim 41, wherein said protective material is selected from poly(vinyl alcohol), polymethyl ether, polymethylacrylamide, doped polythiophene, polyethylene glycol and doped polyaniline.

Claim 43 (new): A method according to claim 40, wherein said protective material comprises an alcohol soluble polymer.

Claim 44 (new): A method according to claim 40, wherein said protective material comprises polymers that are soluble in polar solvents, dimethyl formamide, or acetonitrile.

Claim 45 (new): A method according to claim 44, wherein said protective material is selected from polystyrene, poly(methylmethacrylate) or poly-ethylene oxide.

Claim 46 (new): A method according to claim 44, wherein said protective material is selected from silicon, silicon nitride and silicon oxide.

Claim 47 (new): A method according to claim 1, wherein said protective material comprises inorganic material.

Claim 48 (new): A method according to claim 1, wherein the functional material is deposited by a method selected from spin coating, evaporation, sputtering and printing.

Claim 49 (new): A method according to claim 1, wherein the protective material is deposited by a method selected from spin coating, spraying, evaporation, printing and sputtering.

Claim 50 (new): A method according to claim 1, wherein said functional material comprises an organic electro-optically active material.

Claim 51 (new): A method according to claim 1, wherein said functional material comprises a biochemical or biological reagent.

Claim 52 (new): A method of making an opto-electronic device, comprising the step of patterning a functional material onto a substrate, said patterning step including:

- (a) applying a layer of functional material to at least one major surface of the substrate;
- (b) applying a layer of protective material, soluble in a solvent in which the functional material is insoluble, over said layer of functional material;
- (c) removing areas of said layers of protective and functional materials in well-defined regions on the substrate; and
- (d) removing the remaining exposed protective material from the substrate by dissolution in said solvent.